

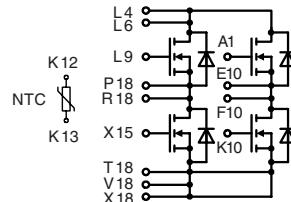
**HiPerFET™ Power MOSFET**

H-Bridge Topology in ECO-PAC 2

N-Channel Enhancement Mode

High dv/dt, Low  $t_{rr}$ , HDMOS™ Family

$I_{D25} = 75 \text{ A}$   
 $V_{DSS} = 100 \text{ V}$   
 $R_{DSon} = 25 \text{ m}\Omega$   
 $t_{rr} \leq 200 \text{ ns}$



Pin arrangement see outlines

**MOSFETs**

Symbol	Conditions	Maximum Ratings		
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	100		V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1 \text{ M}\Omega$	100		V
$V_{GS}$	Continuous	$\pm 20$		V
$V_{GSM}$	Transient	$\pm 30$		V
$I_{D25}$	$T_C = 25^\circ\text{C}$	75		A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	300		A
$I_{AR}$	$T_C = 25^\circ\text{C}$	75		A
$E_{AR}$	$T_C = 25^\circ\text{C}$	30		mJ
$dv/dt$	$I_S \leq I_{DM}$ , $di/dt \leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$ , $R_G = 2 \Omega$	5		V/ns
$P_D$	$T_C = 25^\circ\text{C}$	300		W

Symbol	Conditions	Characteristic Values		
		( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	100		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 4 \text{ mA}$	2.0		V
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}_{DC}$ , $V_{DS} = 0$		$\pm 100$	nA
$I_{DSS}$	$V_{DS} = 0.8 \cdot V_{DSS}$ ; $T_J = 25^\circ\text{C}$ $V_{GS} = 0 \text{ V}$ ; $T_J = 125^\circ\text{C}$		250	$\mu\text{A}$
			1	mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$ , $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle d $\leq 2\%$		25	$\text{m}\Omega$
$g_{fs}$	$V_{DS} = 10 \text{ V}$ ; $I_D = I_{D25}$ , pulse test	25	30	S
$C_{iss}$		4500		pF
$C_{oss}$	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	1600		pF
$C_{rss}$		800		pF
$t_{d(on)}$		20	30	ns
$t_r$	$V_{GS} = 10 \text{ V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 0.5 I_{D25}$	60	110	ns
$t_{d(off)}$	$R_G = 2 \Omega$ , (External)	80	110	ns
$t_f$		60	90	ns
$Q_{g(on)}$		180	260	nC
$Q_{gs}$	$V_{GS} = 10 \text{ V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 0.5 I_{D25}$	36	70	nC
$Q_{gd}$		85	160	nC
$R_{thJC}$		0.5	K/W	
$R_{thCK}$	with heatsink compound (0.42 K/m.K; 50 $\mu\text{m}$ )	0.25	K/W	

**Features**

- HiPerFET™ technology
  - low  $R_{DSon}$
  - low gate charge for high frequency operation
  - unclamped inductive switching (UIS) capability
  - dv/dt ruggedness
  - fast intrinsic reverse diode
- ECO-PAC 2 package
  - isolated back surface
  - enlarged creepage towards heatsink
  - application friendly pinout
  - low inductive current path
  - high reliability
  - solderable pins for PCB mounting

**Applications**

- drives and power supplies
- battery or fuel cell powered
- automotive, industrial vehicle etc.
- secondary side of mains power supplies

IXYS reserves the right to change limits, test conditions and dimensions.

## Source-Drain Diode

## Characteristic Values

( $T_1 = 25^\circ\text{C}$ , unless otherwise specified)

Symbol		Conditions	min.	typ.	max.
$I_s$		$V_{GS} = 0 \text{ V}$			75 A
$I_{SM}$		Repetitive;			300 A
$V_{SD}$		$I_F = I_{D25}, V_{GS} = 0 \text{ V},$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2\%$			1.75 V
$t_{rr}$		$I_F = 25 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}, \quad T_J = 25^\circ\text{C}$ $V_R = 25 \text{ V} \quad \quad \quad T_J = 125^\circ\text{C}$		300	200 ns ns

## Temperature Sensor NTC

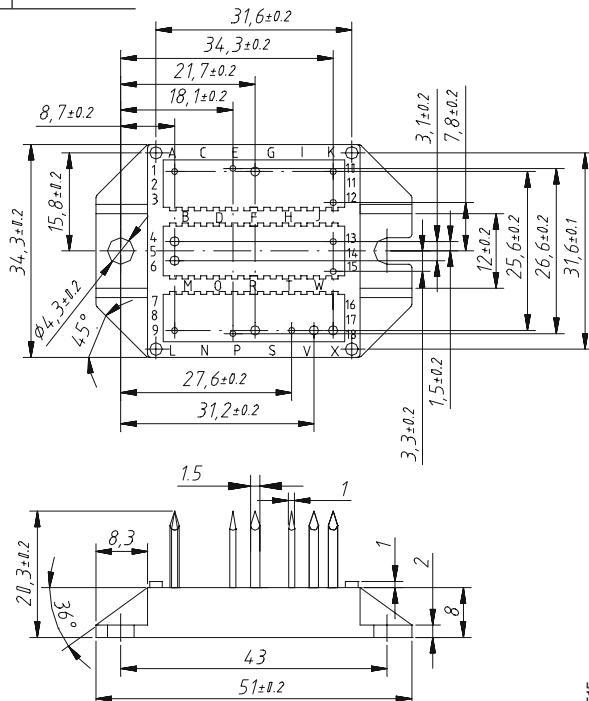
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R <sub>25</sub>	T = 25°C	4.75	5.0	5.25 kΩ
B <sub>25/50</sub>			3375	K

## Module

Symbol	Conditions	Maximum Ratings	
$T_{VJ}$		-40...+150	°C
$T_{stg}$		-40...+125	°C
$V_{ISOL}$	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}; t = 1 \text{ s}$	3600	V~
$M_d$	mounting torque (M4)	1.5 - 2.0 14 - 18	Nm lb.in.
$a$	Max. allowable acceleration	50	$\text{m/s}^2$

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$d_s$	Creepage distance on surface (Pin to heatsink)	11.2		mm
$d_A$	Strike distance in air (Pin to heatsink)	11.2		mm
Weight			24	g

**Dimensions in mm (1 mm = 0.0394")**



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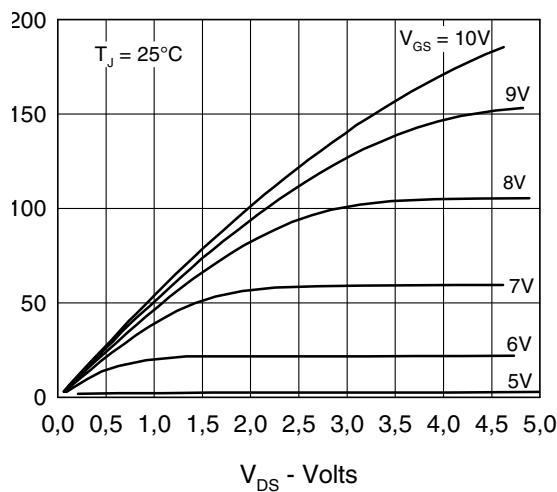


Fig. 1 Output Characteristics

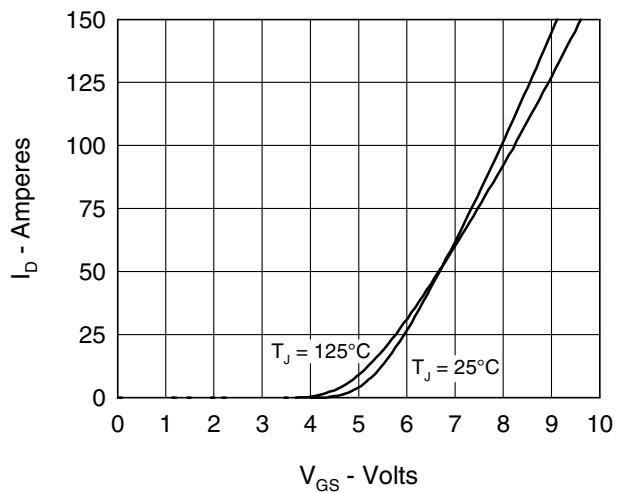


Fig. 2 Input Admittance

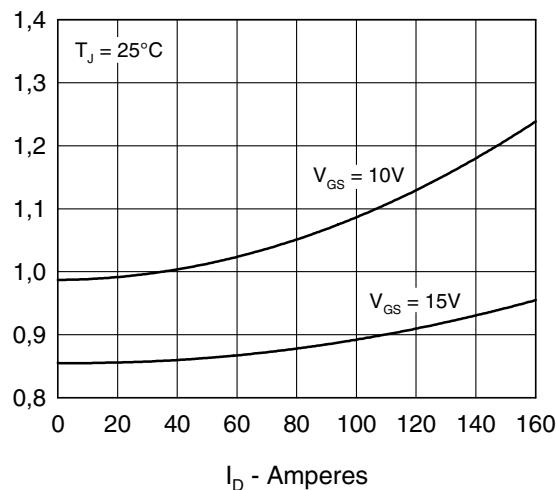
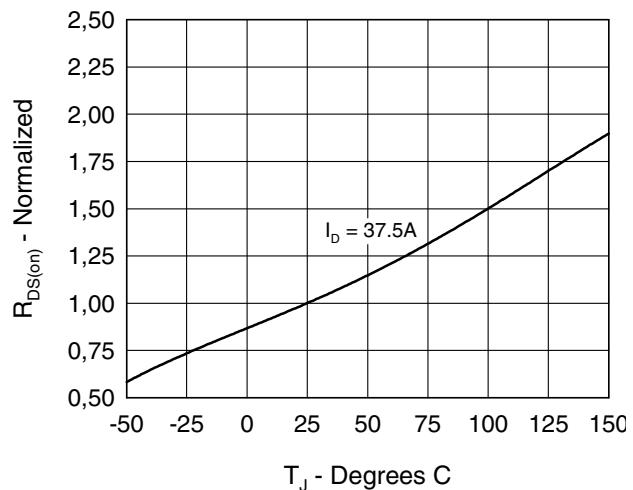
Fig. 3  $R_{DS(on)}$  vs. Drain Current

Fig. 4 Temperature Dependence of Drain to Source Resistance

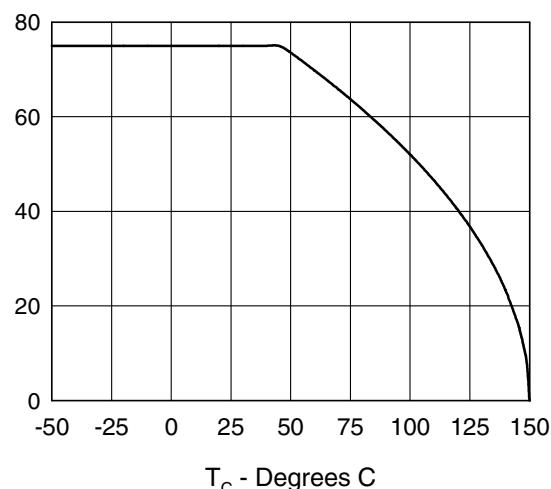


Fig. 5 Drain Current vs. Case Temperature

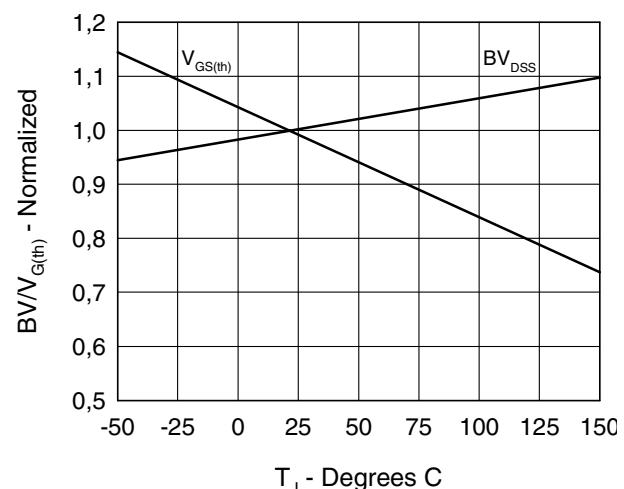


Fig. 6 Temperature Dependence of Breakdown and Threshold Voltage

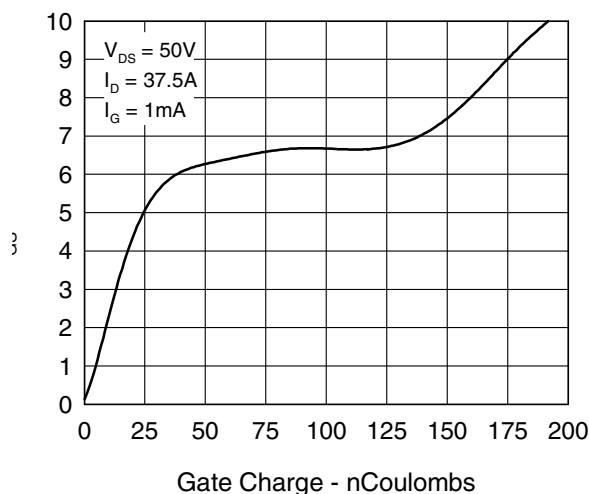


Fig.7 Gate Charge Characteristic Curve

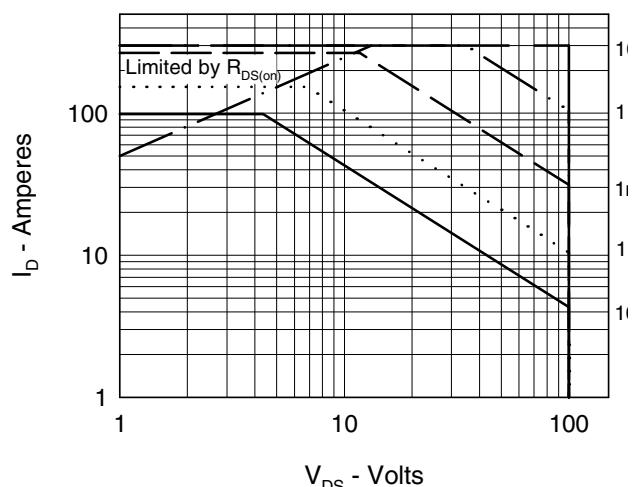


Fig.8 Forward Bias Safe Operating Area

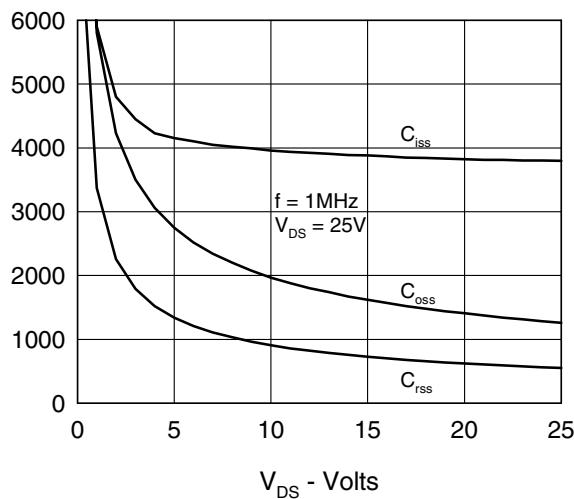


Fig.9 Capacitance Curves

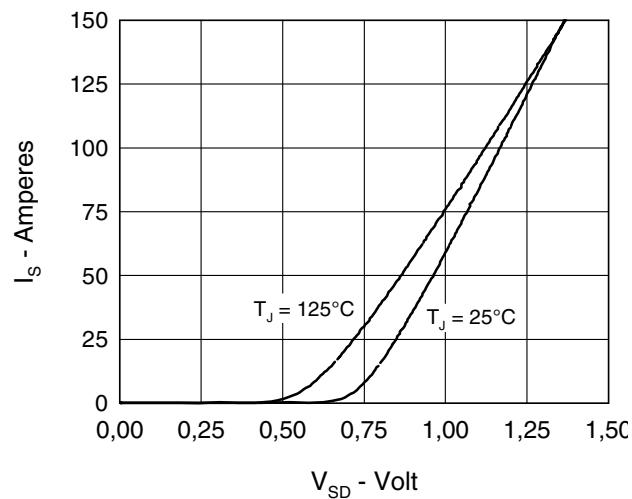


Fig.10 Source Current vs. Source to Drain Voltage

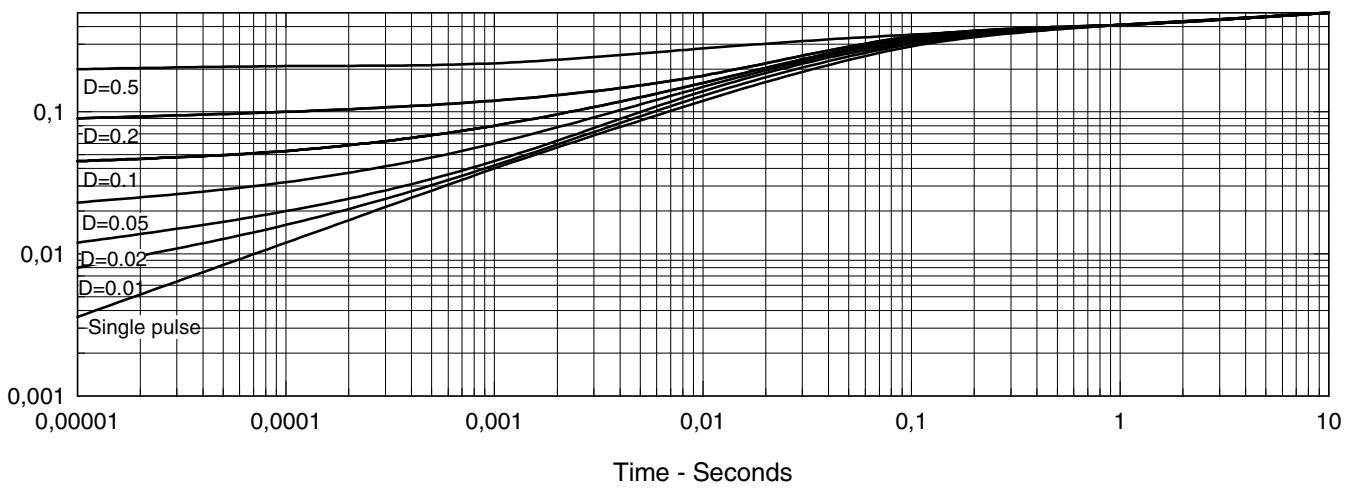


Fig.11 Transient Thermal Impedance